

The 5th International Conference on Engineering, Physics, MEMS-Biosensors and Applications (ICEBA2024)

Host by: VNUHCM-University of Science (Vietnam),
Tohoku University (Japan) & Mien Tay Construction University (Vietnam)
November 11&12, 2024

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Nguyen Phuoc Hoang Khang

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Important Dates (2024)

- Abstract submission: **Jun 10**

- Acceptance notification: **Jul 10**

- Full paper submission: **Sep 10**

- Registration and Payment: **Oct. 10**

- Session schedule: **Oct 30**

- Conference day: **Nov 11&12**

The Secretariats

*Faculty of Physics and Engineering

Physics (Building A), VNUHCM-US

* Institute of S&T Cooperation, MTU

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The purpose of the 5th ICEBA2024 is to link the researchers and scientists from Vietnam and countries around the world, especially Asian countries, in the fields of engineering, physics, microelectronics, semiconductors, and electronic engineering for their applications in biomedical engineering, health sciences, hi-tech agriculture, and smart cities. Besides, we also contribute to promoting international cooperation activities by joining research projects and international co-publications and proposing good solutions and applied technology for the development of the Mekong delta area.

The subject areas: Contributed papers must be the new research works and are solicited in the following subject areas (but not limited to):

- *Physics, Engineering Physics, Electrical & Electronic Engineering;*
- *Medical Physics and Nuclear Engineering;*
- *MEMS (MicroElectronMechanical System), Sensors, Biosensors and semiconducting devices;*
- *Microelectronics, IC design, low consumption devices, Renewable Energy*
- *Computing Science, Simulations and Modeling;*
- *Embedded systems, Internet of Things, Machine Learning, Artificial Intelligence,..*
- *Biomedical Engineering, Digital Microfluidics and their applications;*
- *Civil and Geology Engineerings;*
- *Constructions, Machines and Mechanical Engineering;*

More information: <https://phys.hcmus.edu.vn/ICEBA2024/#/>

Please submit your abstract (around 200 words) via the EasyChair link: <https://easychair.org/conferences/?conf=5thiceba2024> before **June 10th, 2024**.

Full paper for review process of publication (use template) must be submit before **September 10th, 2024**.

Publications: The selected papers (from 4 to 8 pages) will be reviewed or recommended in one of three below Scopus/SCIE/Scimago database Journal (1,2,3) or Vietnamese Journal (4) with fee such as:

- (1) *The special issue of Applied Science (MDPI, Scopus, IF:5.3, Q1/Q2);*
- (2) *IEEEJ Transactions on Electrical and Electronic Engineering (Scopus, Q3);*
- (3) *The special issue of ICEBA on IEEEJ-TSC (Scopus, Q4);*
- (4) *Journal of Construction (Ministry of Construction, Vietnam, ISSN 2734-9888).*

Host: VNUHCM-University of Science, Tohoku University (Japan) and Mien Tay Construction University (Vietnam).

Technical Supports: Institute Electrical Engineer of Japan (IEEJ), IEEE Vietnam Section, Institute of Korean Electrical & Electronic Engineers (IKEEE) and HoChiMinh Semiconducting Industrial Association (HSIA).

***Co-organizers**

***Technical Support**

